Final Product Change Notification

202008021F01

Issue Date: 20-Sep-2020
Effective Date: 18-Dec-2020

Management Summary

NXP is changing the packing format from tray to brick for 72 LPC Microcontroller products.

Change Category

- ☐ Wafer Fab Process
- ☐ Wafer Fab Materials
- ☐ Wafer Fab Location
- ☐ Firmware
- ☐ Assembly Process
- ☐ Assembly Materials
- ☐ Assembly Location
- ☐ Other
- ☐ Product Marking
- ☐ Mechanical Specification
- ☑ Packing/Shipping/Labeling
- ☐ Test Location
- ☐ Test Process
- ☐ Test Equipment
- ☐ Design
- ☐ Errata
- ☐ Electrical spec./Test coverage

LPC Microcontroller Product Tray to Brick Packing Change

Description of Change

NXP is changing the packing format from single-tray to 5-tray (brick) for 72 LPC Microcontroller products.

This will result in the creation of new part numbers to order and new Minimum Order Quantities (MOQs). A complete list with the new orderable part numbers, including the new packing and MOQ is attached for your reference.

There is no change to the products, only the packing method and packing quantity.

The Distributor Price Book has been updated with new part numbers.

Upon the effective date of this PCN, NXP will only accept purchase orders for limited quantities of the old (single tray) packing.

Reason for Change

This change will bring significant freight cost savings to our customers by decreasing the use of boxes and shipping volume by 60-80% on average.

Identification of Affected Products

Replacement part type created, see Parts Affected list

Product Availability

Sample Information

Not applicable

Production

Planned first shipment 16-Nov-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 20-Oct-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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